Abstracts

A highly integrated dual-band tri-mode transceiver chipset for CDMA TIA/EIA-95 and AMPS applications (2000 [RFIC])

T. Robinson, B. Agarwal, S. Lloyd, P. Piriyapoksombut, K. Rampmeier, M. Reddy and D. Yates. "A highly integrated dual-band tri-mode transceiver chipset for CDMA TIA/EIA-95 and AMPS applications (2000 [RFIC])." 2000 Radio Frequency Integrated Circuits (RFIC) Symposium 00. (2000 [RFIC]): 249-252.

In this paper, a two device chip-set integrating the RF transceiver front-end function for the dual-band, dual-mode CDMA/AMPS cellular telephone standard TIA/EIA-98 is described. Fabricated in a double-polysilicon, 25 GHz f/sub T/, silicon bipolar process, the transceiver achieves a total power dissipation of less than 480 mW at 3 V with 9 dBm transmitter power.

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